DECLARATION FOR PATENT APPLICATION (WITH POWER OF ATTORNEY)

As an inventor name below or on any attached continuation page, I hereby declare that:

yesidence, post fiftice address and citizenship are as stated next to my name.

I below the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled QUAD FLAT NO LEAD (QFN) GRID ARRAY PACKAGE, METHOD OF MAKING MEMORY MODULE AND COMPUTER SYSTEM INCLUDING SAME, the specification of which (check one):

☐ is attached hereto. ■ was filed on August 20, 2001 as United S ☐ was filed on as PCT internat	tates application serial no. 09/933,297. ional application no and was a	mended under PCT Article 19	on	
I hereby state that I have reviewed and under referred to above.	stand the contents of the above-identified sp	ecification, including the claim	ms, as amended by	any amendment
I acknowledge the duty to disclose to the U.S matter claimed in this application, as "materialit			il to the patentabil	ity of the subject
I hereby claim foreign priority benefits unde certificate or § 365(a) of any PCT international attached continuation page and have also identifi PCT international application(s) designating at lewhich priority is claimed.	application(s) designating at least one count ed below and on any attached continuation	ry other than the United States	s of America listed or patent or invent	below and on any or's certificate or any
Prior foreign/PCT application(s):			n	
200104675-4	Singapore	06/08/2001	Priority Claimed X Yes No	
(number)	(country)	(day/month/year filed)	Yes	No
(number)	(country)	(day/month/year filed)	Yes	No
I hereby claim the benefit under Title 35, Undesignating the United States of America listed application is not disclosed in any such prior application to disclose to the U.S. Patent and Tradema Regulations § 1.56 which became available between	pelow and on any attached continuation page olication in the manner provided by the first rk Office all information known to me to be been the filing date of such prior application	e and, insofar as the subject m paragraph of Title 35, United material to patentability as de and the national or PCT inter	atter of each of the states Code, § 11 affined in Title 37, mational filing date	e claims of this 12, I acknowledge the Code of Federal e of this application:
(application serial no.)	(filing date)	(status - pending, patented or abandoned)		
(application serial no.)	(filing date)	(status - pending,	patented or aband	oned)
I hereby claim the benefit under Title 35, Un	nited States Code, § 119(e) of any United St	ates provisional application(s)	listed below:	
(provisional application no.)	(filing date)			
I hereby appoint the following Registered Pretherewith: David V. Trask, Reg. No. 22,012 Joseph A. Walkowski, Reg. No. 28,765 Allen C. Turner, Reg. No. 33,041 Brick G. Power, Reg. No. 38,581 Krista Weber Powell, Reg. No. 47,867 Shawn G. Hansen, Reg. No. 42,627	William S. Britt, Reg. No. 20,969 James R. Duzan, Reg. No. 28,393 Edgar R. Cataxinos, Reg. No. 39,931 Paul C. Oestreich, Reg. No. 44,983 Jarett K. Abramson, Reg. No. 47,376 Bretton L. Crockett, Reg. No. 44,632	Laurence B. Bond, F. H. Dickson Burton, J. Kent S. Burningham. Devin R. Jensen, Re David L. Stott, Reg. Bradley B. Jensen, R.	Reg. No. 30,549 Reg. No. P-48,39 Reg. No. 30,453 g. No. 44,805 No. 43,937 Reg. No. 46,801	96
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I hereby declare that all statements made her and further that these statements were made wit both, under Section 1001 of Title 18 of the Unit issued thereon.	h the knowledge that willful false statements	and the like so made are pun	ishable by fine or	imprisonment, or
Full name of first joint inventor: Setho Sing Fe Inventor's signature Residence: Singapore Citizenship: Republic of Singapore Post Office Address: Block 91, Bedok North St		_ Date10/29	/61	

Invention title: QUAD FLAT NO LEAD (QFN) GRID ARRAY PACKAGE, METHOD OF MAKING MEMORY MODULE AND COMPUTER SYSTEM

INCLUDING SAME

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